Materials Declaration

Package	TSSOP
Body Size	4.4
LeadCount	16
Option	Pb-Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Byphenyl resin	9	1.00 E-03	15738
SiO2 Filler	85	9.48 E-03	148639
Phenol Resin	5	5.58 E-04	8743
Antimony_Sb2O3	0.5	5.58 E-05	874
Brominated Resin	0.5	5.58 E-05	874

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	3.52 E-02	552150
Ni	3	1.10 E-03	17219
Si	0.65	2.38 E-04	3731
Mg	0.15	5.49 E-05	861

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	5.00 E-04	7838

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	1.42 E-03	22215

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.13 E-04	4909

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	1.36 E-02	212859

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	5.34 E-05	838
Ag Filler	75	1.60 E-04	2513

Package Totals

Weight (g)	PPM
6.38 E-02	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	ICP AES
Cd	Not Detected	ICP AES
Hg	Not Detected	ICP AES
Cr+6	Not Detected	DIN 53314
PBB	Not Detected	ICP AES
PBDE	Not Detected	ICP AES

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

AMK-RU-D

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability tc
any inaccuracy of such information.

ADI Proprietary

Materials Declaration

Package	TSSOP
Body Size	4.4
LeadCount	16
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Byphenyl resin	9	1.00 E-03	15738
SiO2 Filler	85	9.48 E-03	148639
Phenol Resin	5	5.58 E-04	8743
Antimony_Sb2O3	0.5	5.58 E-05	874
Brominated Resin	0.5	5.58 E-05	874

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	3.52 E-02	552150
Ni	3	1.10 E-03	17219
Si	0.65	2.38 E-04	3731
Mg	0.15	5.49 E-05	861

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	5.00 E-04	7838

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	1.20 E-03	18882
Pb	15	2.13 E-04	3332

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.13 E-04	4909

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	1.36 E-02	212859

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	5.34 E-05	838
Ag Filler	75	1.60 E-04	2513

Package Totals

Weight (g)	PPM
6.38 E-02	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	ICP AES
Cd	Not Detected	ICP AES
Hg	Not Detected	ICP AES
Cr+6	Not Detected	DIN 53314
PBB	Not Detected	ICP AES
PBDE	Not Detected	ICP AES

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

AMK-RU-A

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any inaccuracy of such information.

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